



JMC ELECTRONICS CO., LTD

TAIEX : 6552

- * JMC's statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- * Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



-Professional Reel-to-Reel Fine-Pitch Service

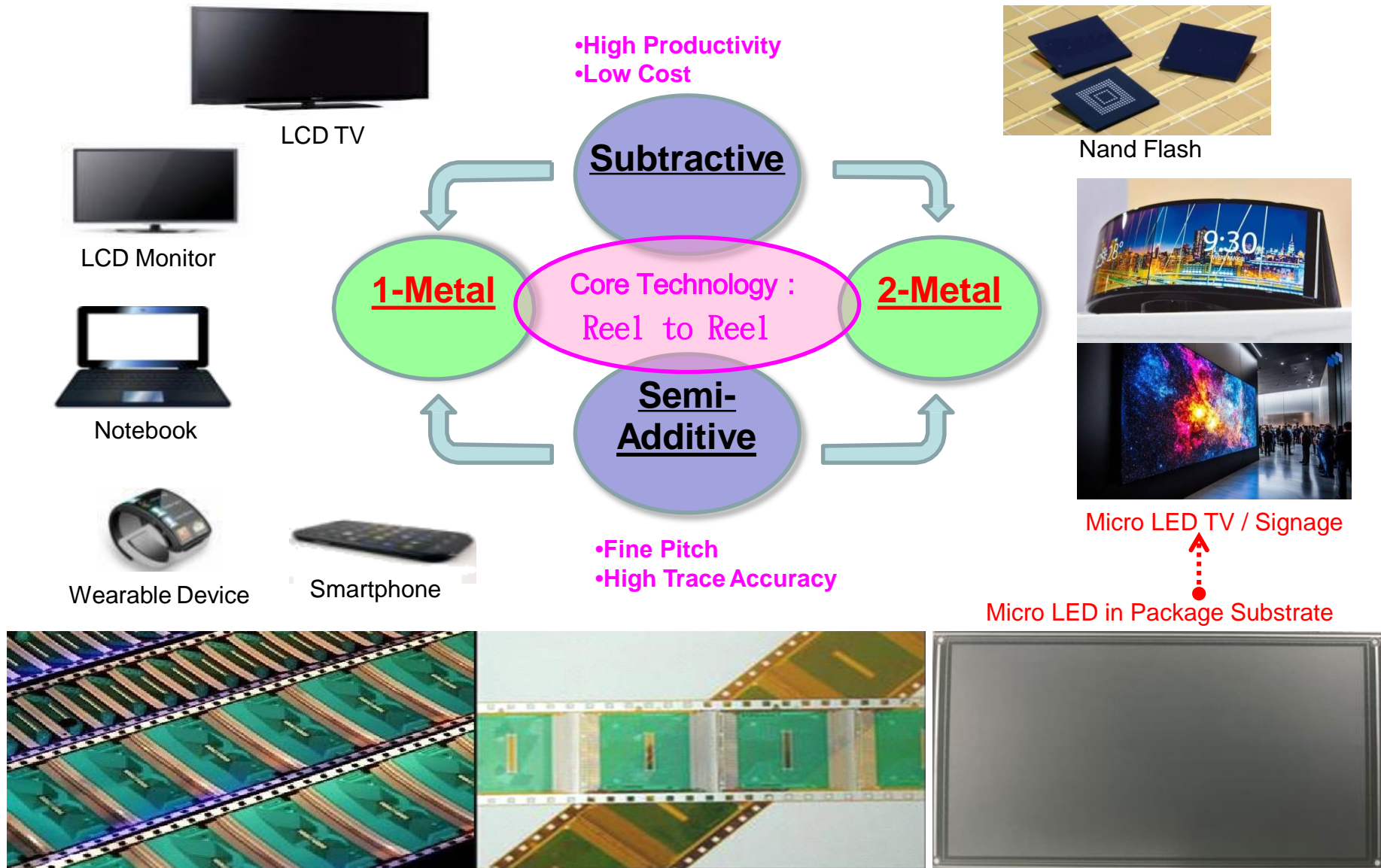
1.Company Introduction - Company Snapshot

- Established : October 6 ,1973
- Chairman : WAN WEN-TSAI
- General Manager : Jane Lee
- Capital Stock : 830 million
- Major Shareholders : CWE 42.8%、ChipMos 10%
- Number of employees as of Oct. 31,2024 : 661
- Major Product : COF(Reel to Reel Chip on Film)
- Headquarter : Kaohsiung,Taiwan

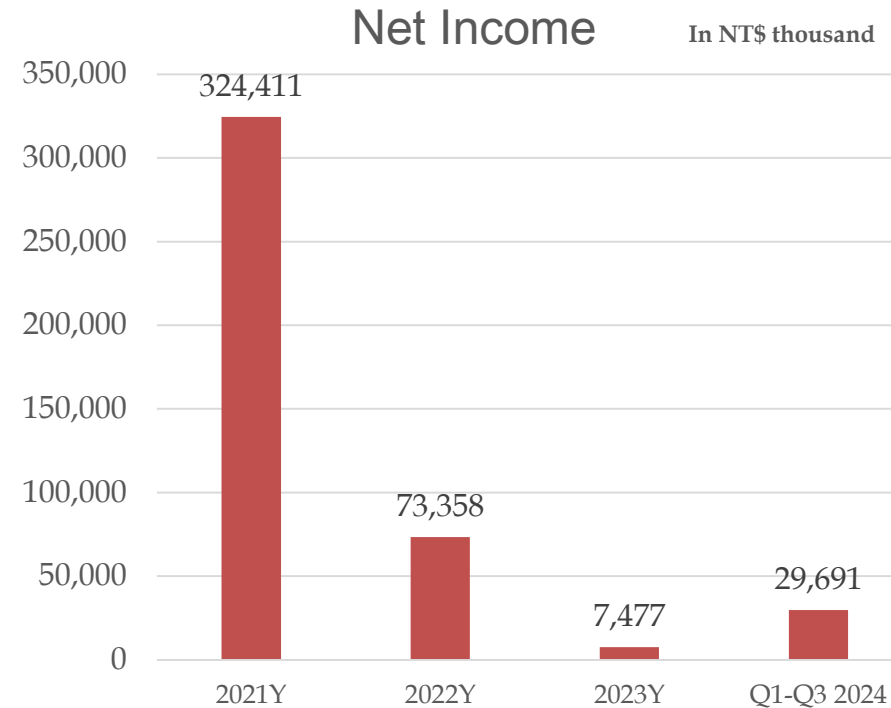
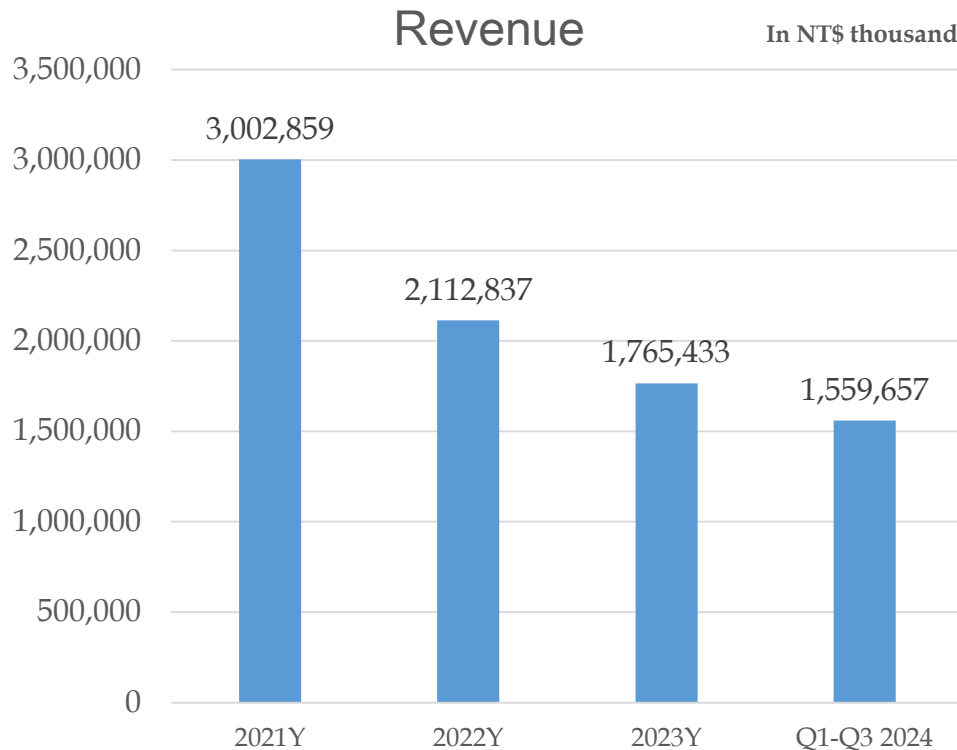


-Professional Reel-to-Reel Fine-Pitch Service

1.Company Introduction - Product Application



2. Financial Results - Historical Revenue and Profitability

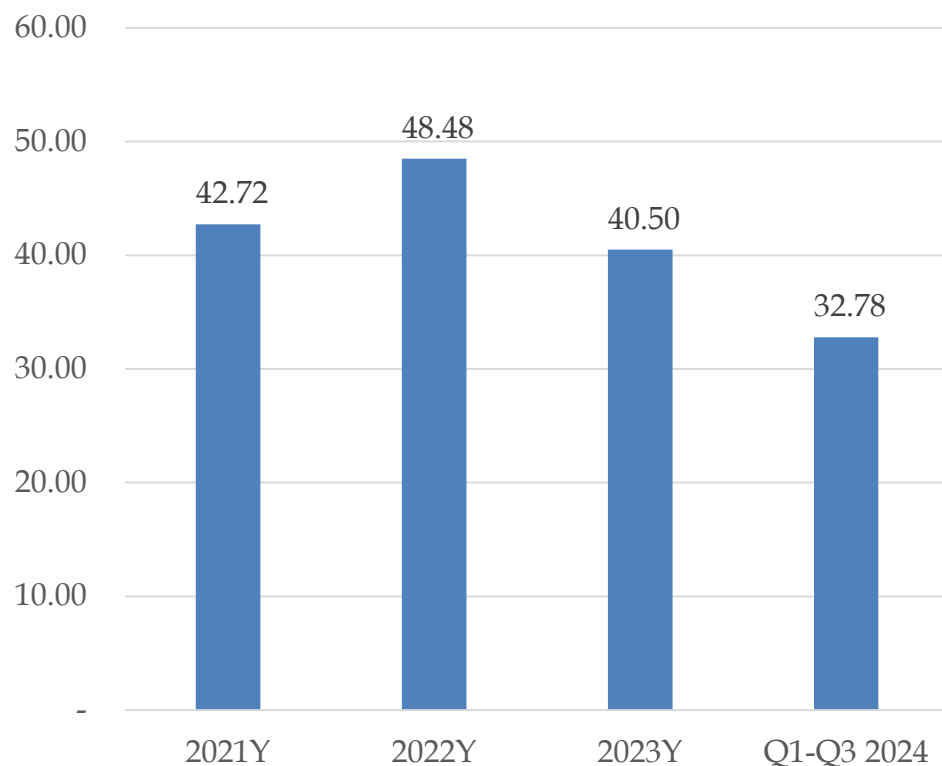


(In NT\$ thousand)

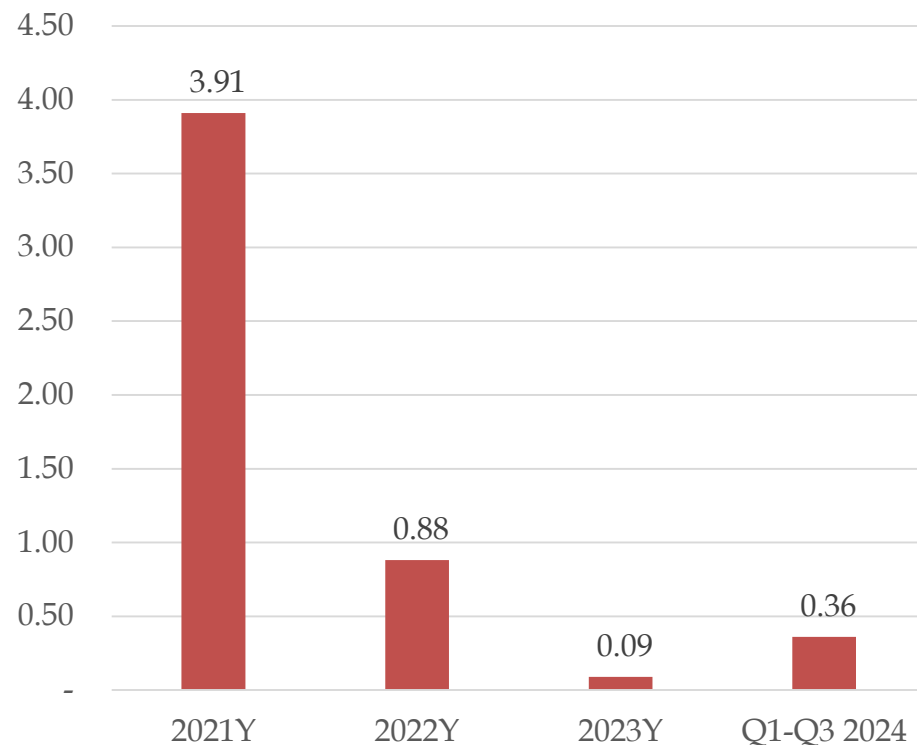
Year	2021	2022	2023	Q1-Q3 2024
Revenue	3,002,859	2,112,837	1,765,433	1,559,657
Net Income	324,411	73,358	7,477	29,691

2. Financial Results - Financial Ratio Analysis

Debt Ratio



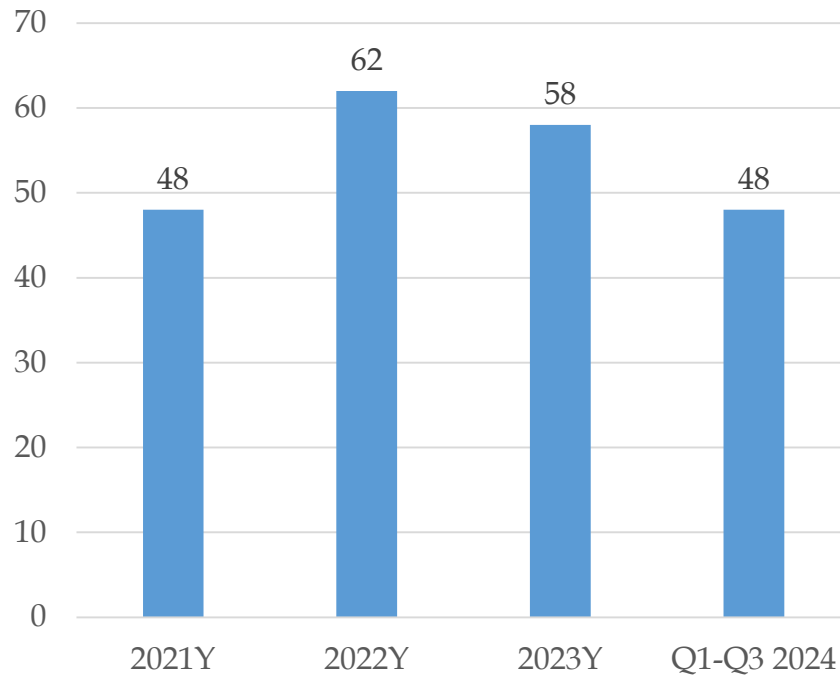
EPS(NT\$)



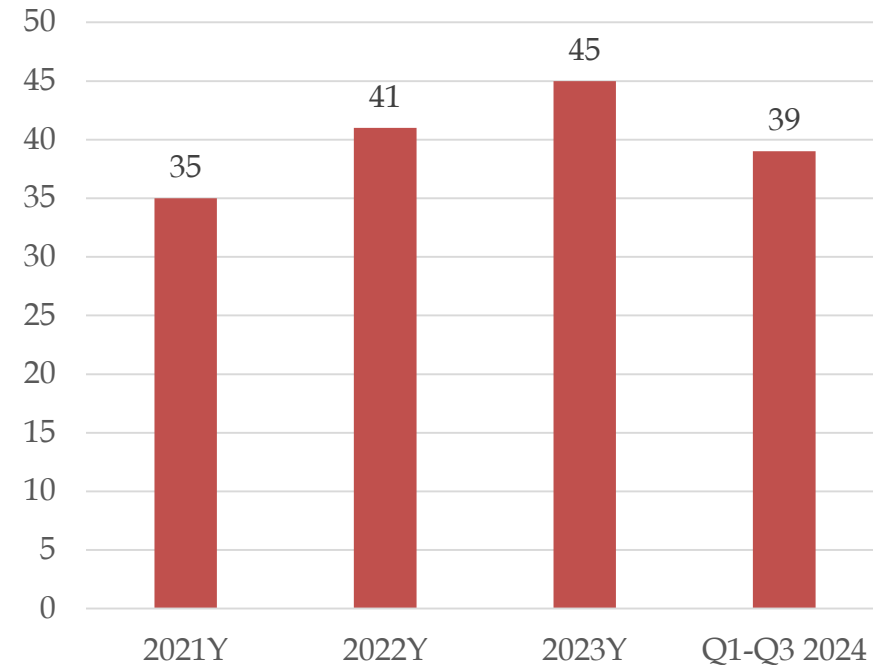
Year	2021	2022	2023	Q1-Q3 2024
Debt Ratio(%)	42.72	48.48	40.5	32.78
EPS(NT\$)	3.91	0.88	0.09	0.36

2. Financial Results - Financial Ratio Analysis

Days of Sales Outstanding

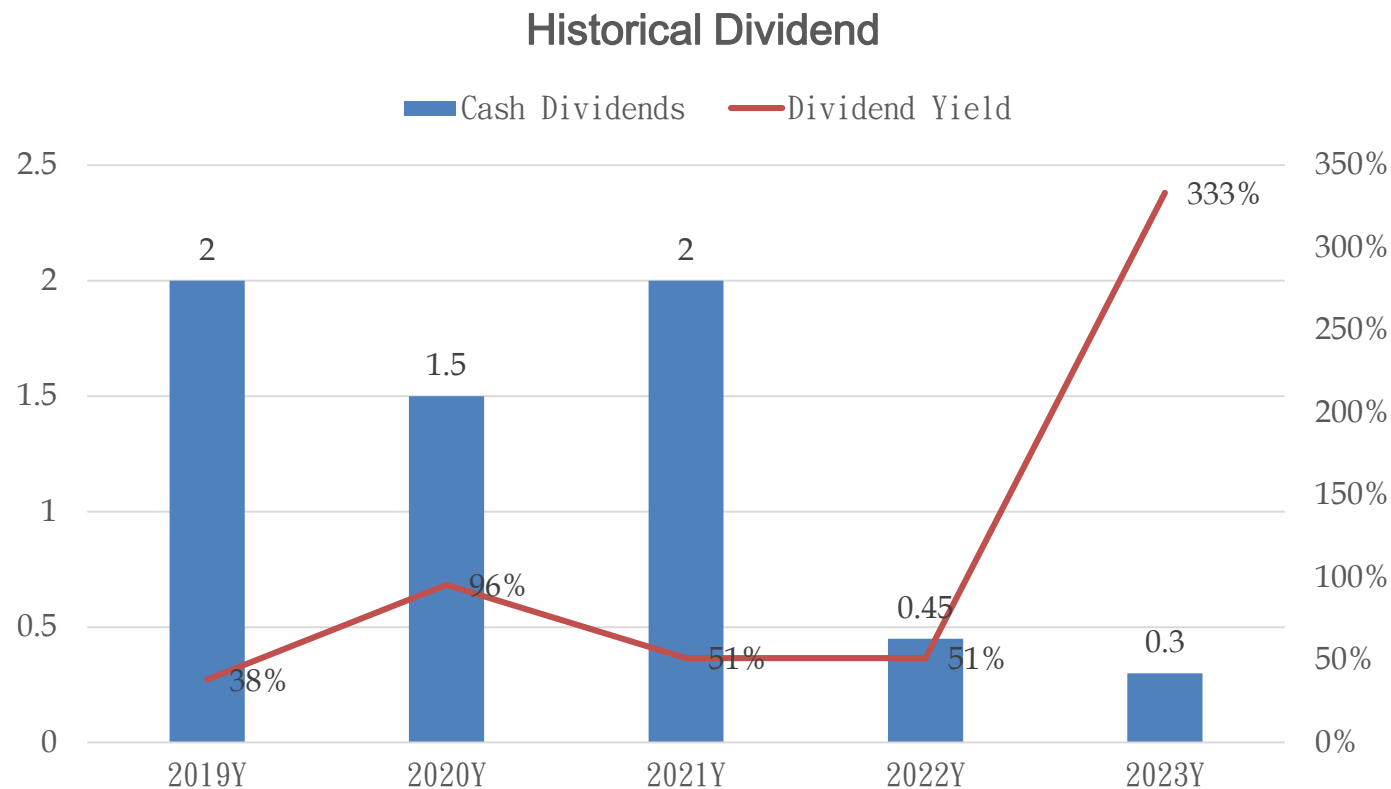


Average days of sales



Year	2021	2022	2023	Q1-Q3 2024
Days of Sales Outstanding	48	62	58	48
Average days of sales	35	41	45	39

2. Financial Results - Historical Dividend



Year	2019	2020	2021	2022	2023
Cash Dividends	2	1.5	2	0.45	0.3
Dividend Yield	38%	96%	51%	51%	333%

3. Market & Business Overview—Panel development trends for different technologies

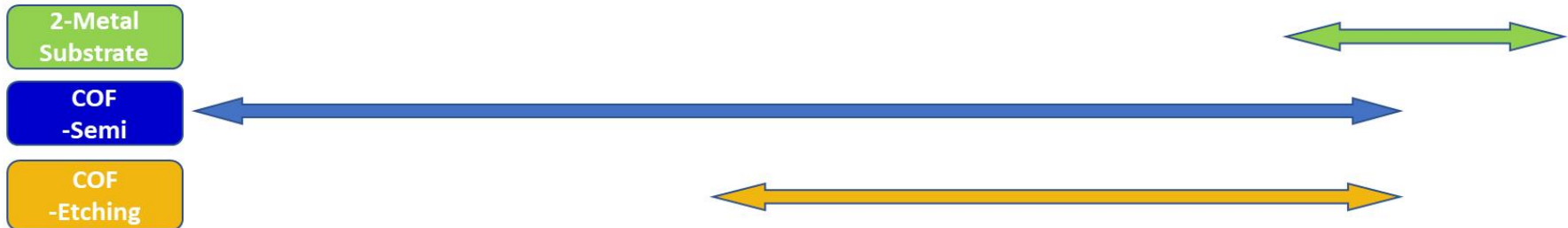
Display technology



Application

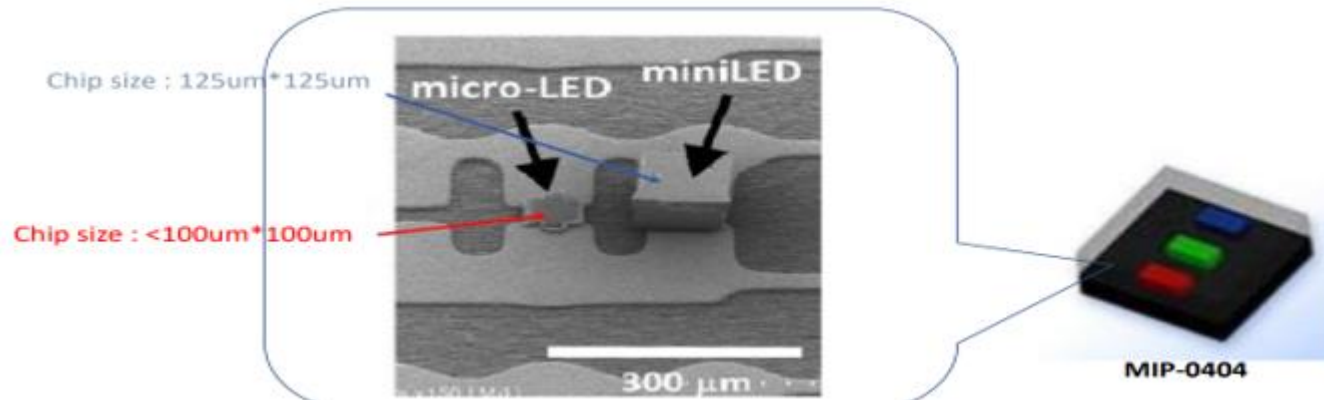


JMC Technology



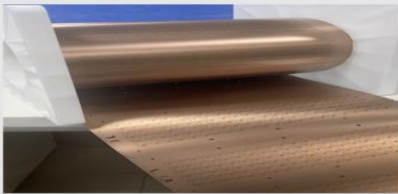
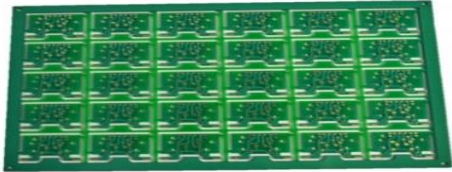
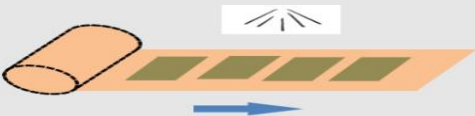

3. Market & Business Overview—MIP(Micro LED in Package)

1. MIP(Micro LED in Package) structure introduction



- When enter the Micro world of Micro products. The miniaturized chips require high-precision and high-resolution PCB (printed Circuit Board) to correspond with and support the large-scale transfer processes. The repeatability requirements for the substrate circuits are extremely high.
- Traditional circuit boards face issues with insufficient precision, while substrates like glass and sapphire are too expensive to manufacture and are not suitable for MIP packaging types. There is a market demand for high-performance substrates that fall between traditional circuit boards and glass substrates.

2. Comparison of MIP Substrate process differences

	Reel to Reel Process (JMC)	Panel Process(Other PCB)
Manufacturing Process		
Manufacturing Form		

3. Market & Business Overview – Market Development

	1-Metal COF	2-Metal IC Substrate
Currently	<p><u>War, Inflation, and stagnant economy affects global demand</u></p> <p>The output value of TV panels and IT panels increased significantly in 2020 and 2021. However, the highly increased market demand was declined since 2022. In 2023, the panel producers continue to reduce production and destocking. The panel market will return to the traditional demand model in 2024, and it is expected to return to a stable demand market in 2025.</p> <p>Driver IC chips of mobile phone panels : the use of COF design was decreasing due to the increasing in COP design.</p> <p>Wearable device with health management functions has become a new trend. Therefore, the COF usage in this field is growing steadily.</p>	<p><u>Mini LED – direct display and backlight market are moving forward together, applications are well-developed</u></p> <p>2021 can be a year of increase in Mini LED-related products, which accelerated the development of next-generation display technology in 2022. All producers published new displays actively, include many Micro LED-related products, which shows the development of the advanced display product market.</p> <p>In 2023, the development and application of Micro LED will become more active.</p> <p>In 2024, that 2 Metal IC Substrate has begun to be used in Micro LED products . °</p> <p>In 2025, JMC's 2 Metal IC Substrate will be used in Micro LED products, and there will be opportunities for mass production.</p>
Future trend	<p><u>New design/application, unchanged trend with delayed demand</u></p> <p>TV Panel – 4K to 8K, the trend has emerged, just waiting for the demand. ↑</p> <p>Monitor/NB/Tablet Panel – COG moves to COF due to full-screen/narrow edge design. ↑</p> <p>Automotive Panel – Starting COF design. ↑</p> <p>Mobile phone panel - using COP/COG design, reducing COF usage. ↓</p> <p>*Wearable Device : The design turns to COF instead of COG due to the narrow edge requirement. The market is still growing up. ↑</p>	<p><u>New design and application</u></p> <p>*The application of Metal IC Substrate for 2 Micro LED will expand and add new customers. ↑</p> <p>*The application fields of other IC Substrate will be expanded. →</p>

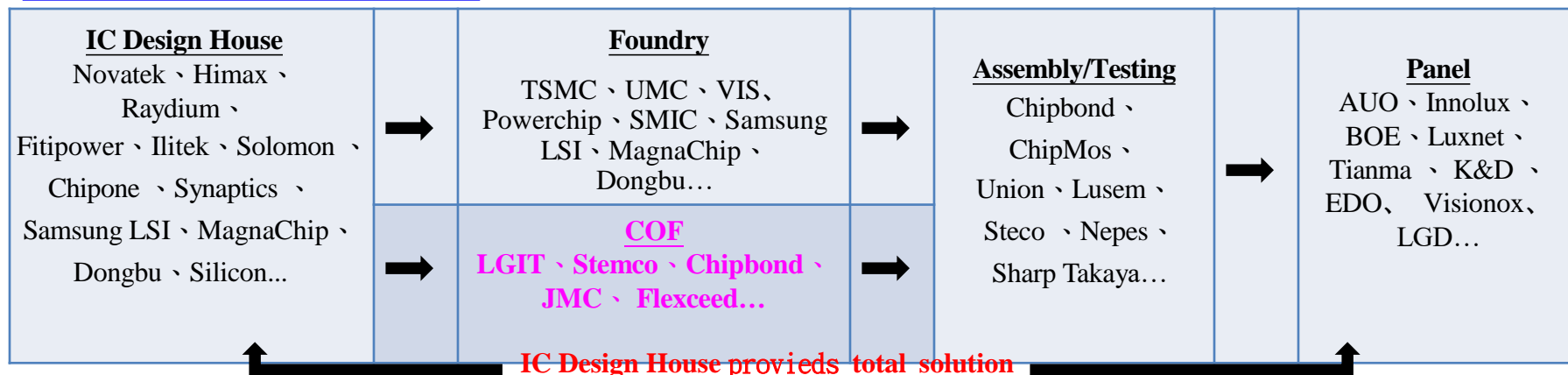
3. Market & Business Overview – Technology & Product

✓ A full service of flexible IC substrate provider

Process Technology	Competitive advantages	Product/ Technical Capabilities	Product application
1-Metal Subtractive (Etching)	<ul style="list-style-type: none">*Fast production and high efficiency.*Independent technical ability and stable production yield.	<ul style="list-style-type: none">*COFCopper thickness #~8umPitch $\geq 20\mu\text{m}$ PitchPin count ≤ 1440 Channel/48mm	<ul style="list-style-type: none">@ TV@ MNT@ NB@ Vehicle
1-Metal Semi-Additive (Plating)	<ul style="list-style-type: none">*High precision size controlled COF products, and can improve the assembly of the panel module rate; help customers to lower total cost.*High production yield and good quality stability; absolute competitive advantage in production costs.	<ul style="list-style-type: none">*COFCopper thickness #~12umPitch $\geq 18/16/14\mu\text{m}$ PitchPin count ≤ 1900 Channel/48mm ≤ 3000 Channel/70mm	<ul style="list-style-type: none">@ TV@ MNT@ NB@ Vehicle@ Wearable 、 Mobile 、 Tablet
2-Metal	<ul style="list-style-type: none">*New process technology development capabilities.*Equipment design capability.*Good cost control.	<ul style="list-style-type: none">*Micro LED IC SubstrateMIP0404MIP0303MIP0202*Thin Film IC Substrate	<ul style="list-style-type: none">@ TV 、 Signage@ NAND Flash

4. Industry Outlook - Driver IC Supply Chain

✓ IC Design House provides total solution.



✓ Five COF suppliers have mass production capacity currently , and JMC is just one of the two vendors in Taiwan.

Process Technology			1-Metal Subtractive(Etching)	1-Metal Semi-Additive(Plating)	2-Metal
Application	Channel/48mm		=<1400 /48mm	1400~1900 /48mm	1900~2500 /48mm
	Channel/70mm		=<2000 /70mm	2000~3000 /70mm	3000~4000 /70mm
Capacity	Korea	S社	90~100KK	?KK(2-Metal→1-Metal)	7-10KK
		L社	120~130KK	?KK(2-Metal→1-Metal)	5-7KK
	Japan	F社	20KK	X	2KK
	Taiwan	C社	70~90KK	X	X
		JMC	40KK	40KK	5KK
	China	ESWIN Aplus	? 15KK	X X	X X

Q&A

